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Application Number 10/553044
Response to Office Action dated 04/16/2007

Amendments to the Claims:

This listing of Claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A chip resistor comprising:

A metal resistor element including a first surface and a second surface opposite to the first surface;

at least two main electrodes spaced from each other and provided on the first surface; and

at least two auxiliary electrodes spaced from each other and provided on the second surface, the auxiliary electrodes facing the main electrodes via the resistor element;

a first insulating layer formed on the resistor element for covering only an area between the main electrodes on the first surface of the resistor element; and

a second insulating layer formed on the resistor element for covering only an area between the auxiliary electrodes on the second surface of the resistor element;

wherein the main electrodes and the auxiliary electrodes are made of a same material.

2. (Original) The chip resistor according to claim 1, wherein a spacing distance between the auxiliary electrodes is no smaller than a spacing distance between the main electrodes.

3. (Cancelled)

4. (Currently Amended) The chip resistor according to claim 1[[3]], wherein a thickness of the first insulating layer is no greater than a thickness of the main electrodes.

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5. (Original) The chip resistor according to claim 1, further comprising at least two solder layers formed on the resistor element,

wherein the resistor element includes a pair of end surfaces spaced from each other, each of the end surfaces being covered by a corresponding one of the two solder layers.

6. (Original) The chip resistor according to claim 5, the solder layers cover the main electrodes and the auxiliary electrodes in addition to the end surfaces of the resistor element.

7. (Currently Amended) The chip resistor according to claim 1[[3]], further comprising a third insulating layer formed on the resistor element, wherein the resistor element includes a side surface extending between the first surface and the second surface, the side surface being covered by the third insulating layer.

8. (Currently Amended) A method of making a chip resistor, the method comprising the steps of:

preparing a metal resistor material including a first surface and a second surface opposite to the first surface;

forming a pattern of first insulating layer on the first surface;

forming a pattern of second insulating layer on the second surface;

forming a pattern of first conductive layer on the first surface for covering portions of the first surface which are not covered with the pattern of insulating layer;

forming a pattern of second conductive layer on the second surface for covering portions of the second surface which are not covered with the pattern of insulating layer;

and

dividing the resistor material into a plurality of resistor elements;

wherein the first conductive layer and the second conductive layer are made of a same material.

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9. (Currently Amended) The method of making chip resistor according to claim 8, wherein the dividing of the resistor material is performed in a manner such that a resulting chip resistor comprises a main electrode made of a part of the first conductive layer and ~~also comprises~~ an auxiliary electrode made of a part of the second conductive layer.

10. (Cancelled)

11. (Currently Amended) The method of making chip resistor according to claim 8[[10]], wherein the pattern forming of the first and second insulating layer layers is formed by thick-film printing.

12. (Currently Amended) The method of making chip resistor according to claim 8[[10]], wherein the first conductive layer and the second conductive layer are formed by metal plating.

13. (Original) The method of making chip resistor according to claim 8, wherein the resistor material is divided by punching or by cutting.

14. (Original) The method of making a chip resistor according to claim 8, further comprising the steps of: forming an insulating layer on a side surface of each resistor element; and forming a solder layer on an end surface of the resistor element by barrel-plating.